

Single-phase DC Brushless Motor Driver IC

■FEATURES

- Supply Voltage $V_{DD}=2.0$ to $5.5V$
- Low Quiescent Current $I_{DD}=1.0mA$ typ.
- Output Voltage $V_{OH}=4.8V$ typ. ($I_O=+350mA$)
 $V_{OL}=0.2V$ typ. ($I_O=-350mA$)
- Input Offset Voltage $V_{IO}=\pm 10mV$ max.
- Closed-loop Gain $A_v=49.8dB$ typ.
- Direct PWM Input
- Lock Protection Function (Auto Recovery)
- FG Output
- Start up Assist Function
- Quick Start Function
- Thermal Shutdown Function
- Operating Temperature $T_{opr}=-40$ to $105^{\circ}C$
- Package Outline MSOP8-Thin (TVSP8)*
*MEET JEDEC MO-187-DA/THIN TYPE

■GENERAL DESCRIPTION

The NJU7367B is a single-phase motor driver IC for small DC brushless motor.

It features Lock Protection, FG Output, Start up Assist, Quick Start and Thermal Shutdown function.

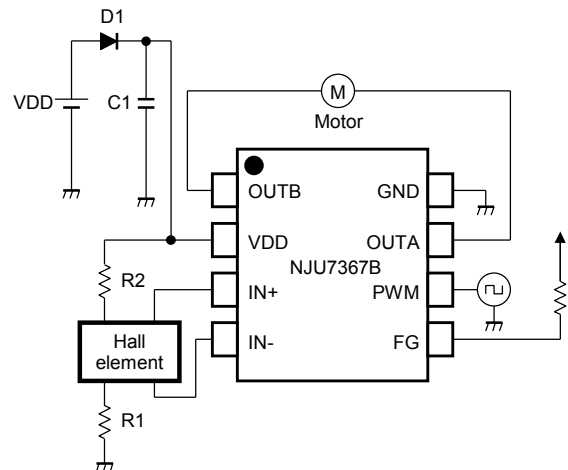
The motor rotational speed is controlled by PWM input signal.

High closed-loop gain and wide operating temperature range make NJU7367B suitable for a small fan motor in high temperature application such as car accessory.

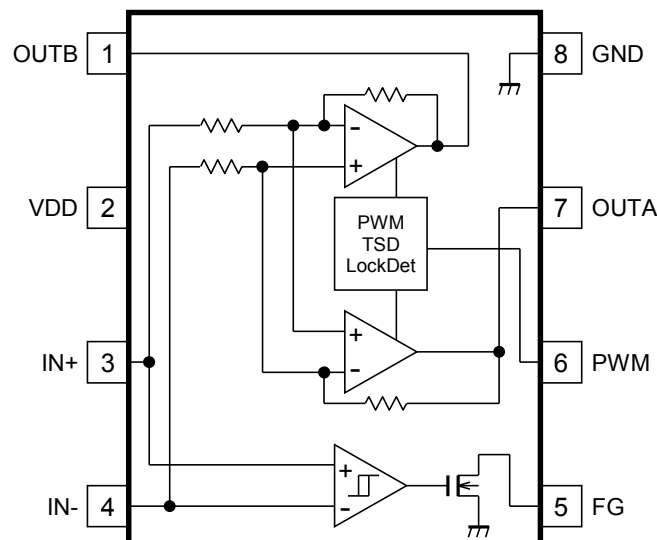
■APPLICATION

Small 5V-FAN Motor

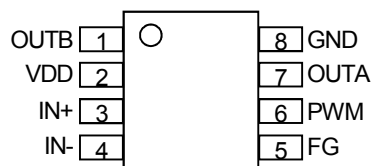
■TYPICAL APPLICATION



■BLOCK DIAGRAM



■PIN CONFIGURATION



PIN NO.	SYMBOL	I/O	DESCRIPTION
1	OUTB	O	Output Pin B
2	VDD	-	Power Supply Pin
3	IN+	I	Input Pin +
4	IN-	I	Input Pin -
5	FG	O	FG Output Pin
6	PWM	I	PWM Input Pin
7	OUTA	O	Output Pin A
8	GND	-	Ground Pin

■PRODUCT NAME INFORMATION



■ORDERING INFORMATION

PRODUCT NAME	PACKAGE OUTLINE	RoHS	HALOGEN-FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ(pcs)
NJU7367BRB1(TE2)	MSOP8-Thin	yes	yes	Sn2Bi	7367B	18	2,000

■ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNIT	NOTE
Supply Voltage	V_{DD}	+7.0	V	VDD Pin
Input Voltage	V_{ID}	-0.3 to V_{DD}	V	IN+, IN- Pin
PWM Input Voltage	V_{PWM}	-0.3 to +7.0	V	PWM Pin
Output Current (Peak)	I_{OPEAK}	1000	mA	OUTA, OUTB Pin
FG Output Current	I_{FG}	10	mA	FG Pin
FG Output Voltage	V_{FG}	+7.0	V	FG Pin
Power Dissipation($T_a=25^{\circ}\text{C}$) MSOP8-Thin	P_D	400 ⁽¹⁾	mW	
		510 ⁽²⁾		
Junction Temperature Range	T_j	-40 to +150	$^{\circ}\text{C}$	
Operating Temperature Range	T_{opr}	-40 to +105	$^{\circ}\text{C}$	
Storage Temperature Range	T_{stg}	-50 to +150	$^{\circ}\text{C}$	

(1): Device itself

(2): Mounted on glass epoxy board. (76.2×114.3×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4)

■RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	RATINGS	UNIT
Supply Voltage	V_{DD}	2.0 to 5.5	V

■ELECTRICAL CHARACTERISTICS

(Unless otherwise noted, $V_{DD}=5\text{V}$, $T_a=25^{\circ}\text{C}$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
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GENERAL

Quiescent Current	I_{DD}	IN+=3.9V, IN-=0.4V	-	1.0	1.5	mA
Thermal Shutdown Operating Temperature	T_{TSD}		-	170	-	$^{\circ}\text{C}$
Thermal Shutdown Hysteresis	T_{HYS}		-	20	-	$^{\circ}\text{C}$

HALL AMP BLOCK

Input Offset Voltage	V_{IO}		-10	-	10	mV
Common Mode Input Voltage Range	V_{ICM}		0.4	-	3.9	V
Closed-loop Gain	A_V		-	49.8	-	dB

OUTPUT BLOCK

Output Voltage	V_{OH}	$I_O=+350\text{mA}$	4.7	4.8	-	V
	V_{OL}	$I_O=-350\text{mA}$	-	0.2	0.3	V
FG L Output Voltage	V_{FG}	$I_{FG}=5\text{mA}$	-	-	0.2	V
FG Leak Current	$I_{FG-LEAK}$	$V_{FG}=5\text{V}$	-	-	1.0	μA

■ ELECTRICAL CHARACTERISTICS

(Unless otherwise noted, $V_{DD}=5V$, $T_a=25^{\circ}C$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
PWM INPUT BLOCK						
PWM Input Frequency	f_{PWM}		2	-	50	kHz
Pullup Resistance	R_{PWM}		-	200	-	k Ω
H Level Input Voltage 1	V_{IHP1}		2.4	-	5	V
L Level Input Voltage 1	V_{ILP1}		0	-	1.4	V
H Level Input Voltage 2	V_{IHP2}	$V_{DD}=2V$	1.1	-	2	V
L Level Input Voltage 2	V_{ILP2}	$V_{DD}=2V$	0	-	0.5	V

LOCK PROTECTION BLOCK

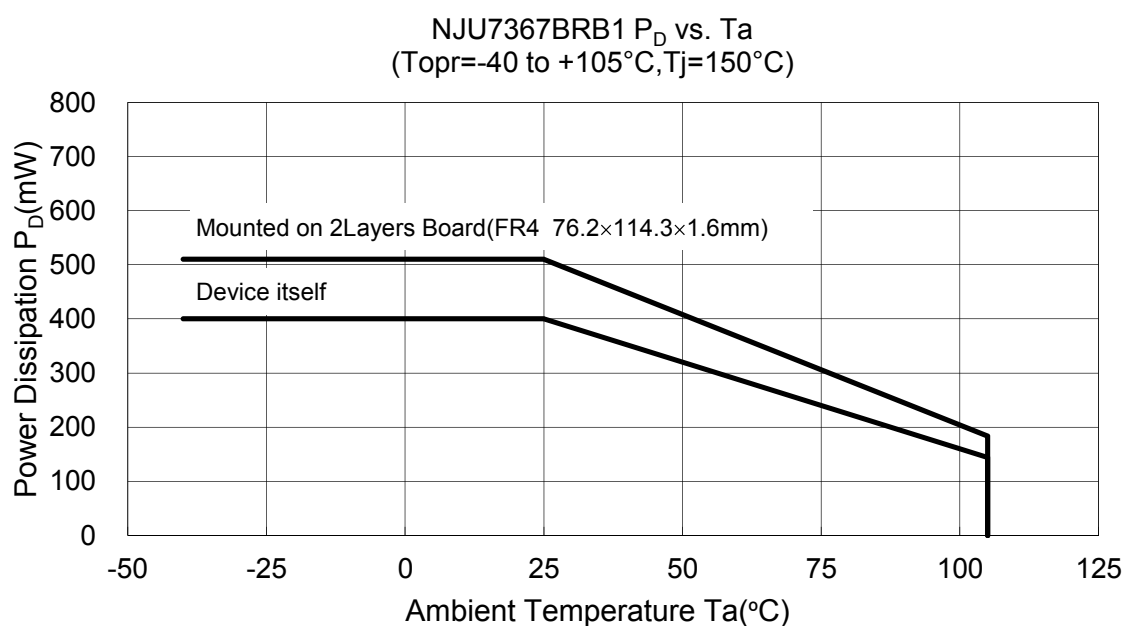
Lock Protection ON Time	t_{ON}		-	0.5	-	s
Lock Protection OFF Time	t_{OFF}		-	5.0	-	s
Lock Protection Ratio	t_{RATIO}		-	1:10	-	-

■ THERMAL CHARACTERISTICS

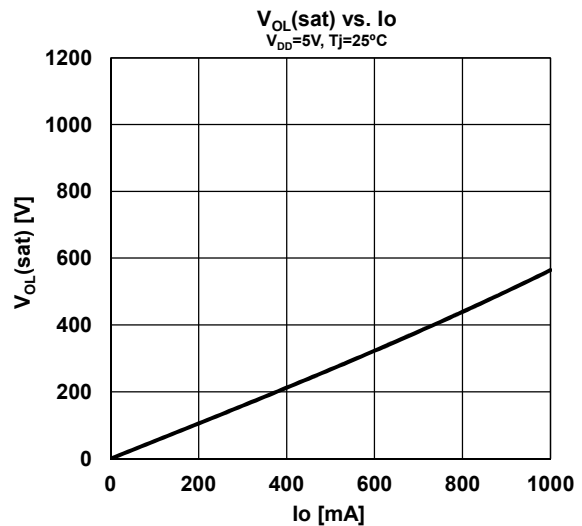
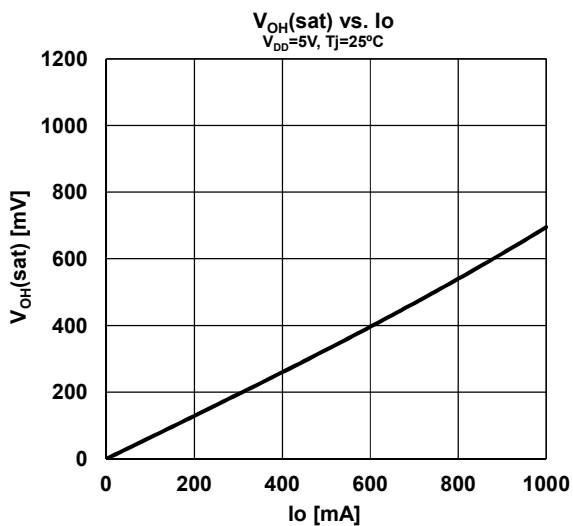
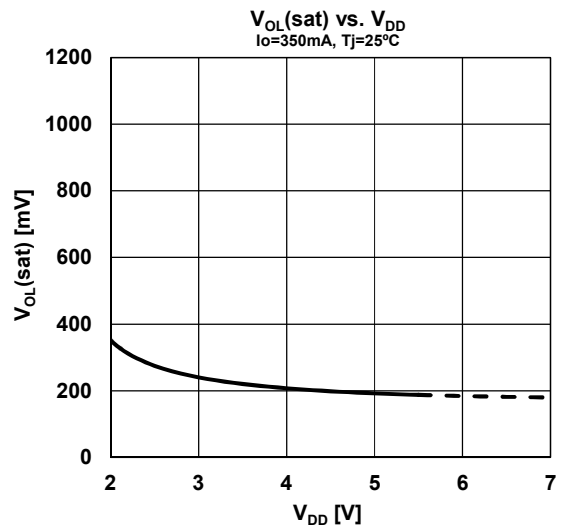
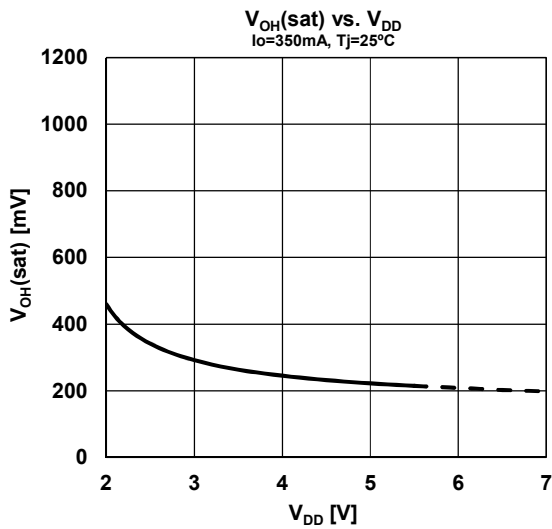
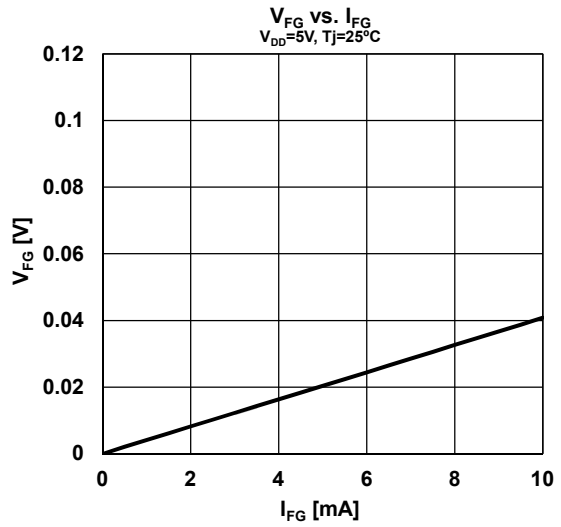
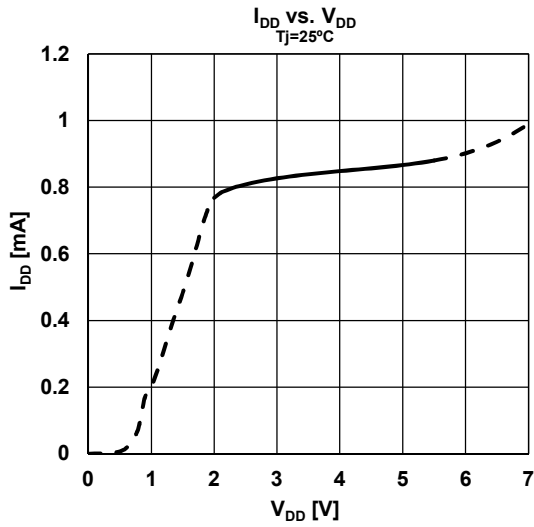
PARAMETER	SYMBOL	VALUE	UNIT
Junction-to-ambient thermal resistance	θ_{ja}	244 ⁽³⁾	$^{\circ}C/W$
Junction-to-Top of package characterization parameter	ψ_{jt}	51 ⁽³⁾	$^{\circ}C/W$

(3): Mounted on glass epoxy board. (76.2×114.3×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4)

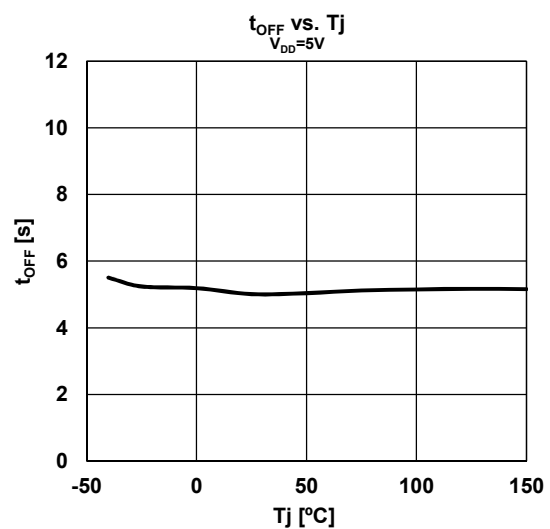
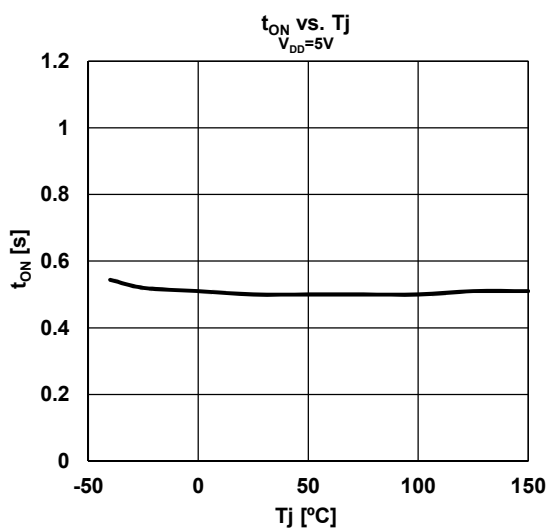
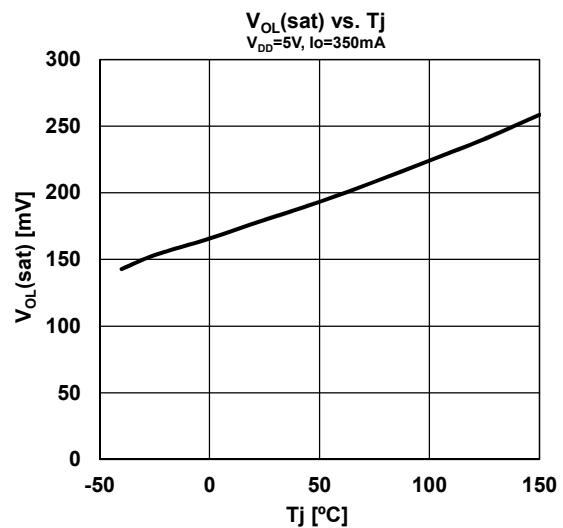
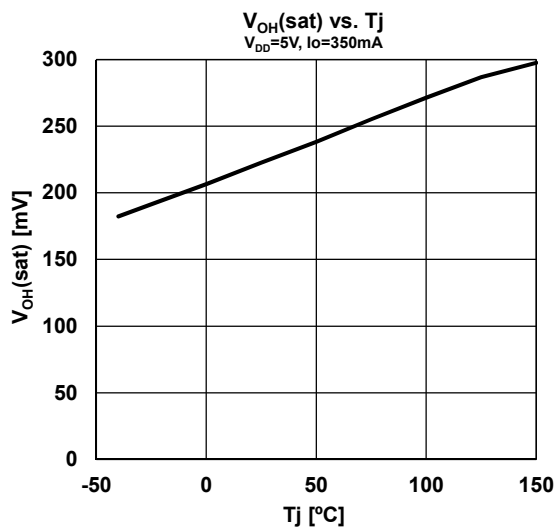
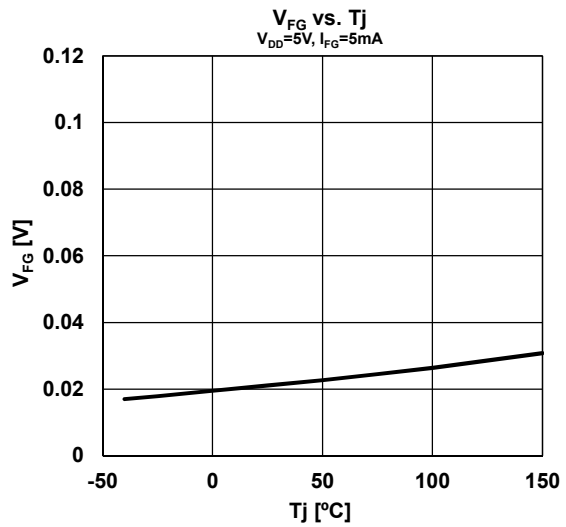
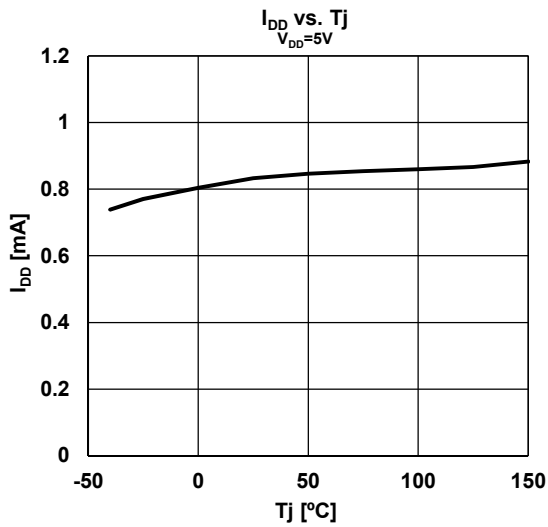
■ POWER DISSIPATION vs. AMBIENT TEMPERATURE



■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS



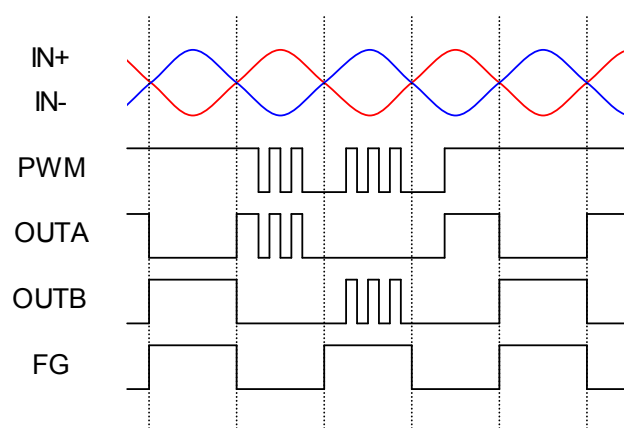
■APPLICATION NOTE / GLOSSARY

●Truth Table

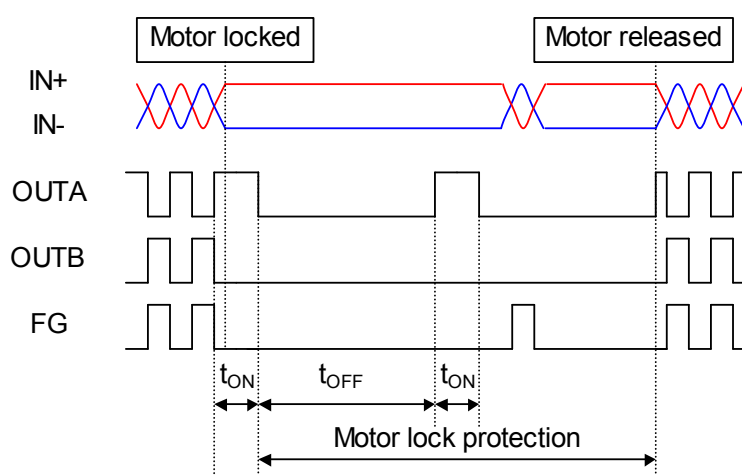
IN+	IN -	PWM	TSD/LD	OUTA	OUTB	FG
H	L	H	OFF	H	L	L
L	H			L	H	Hi-Z
H	L	L		L	L	L
L	H			L	L	Hi-Z
H	L	-	ON	L	L	L
L	H					Hi-Z

●Timing Chart

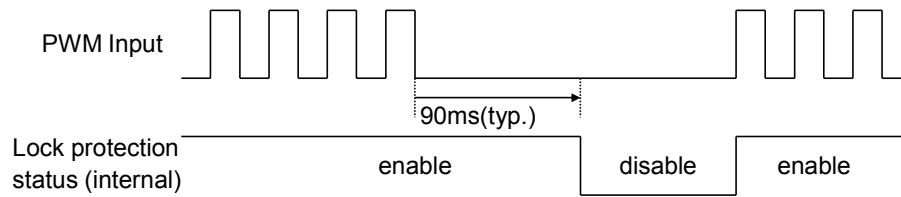
< PWM Input >



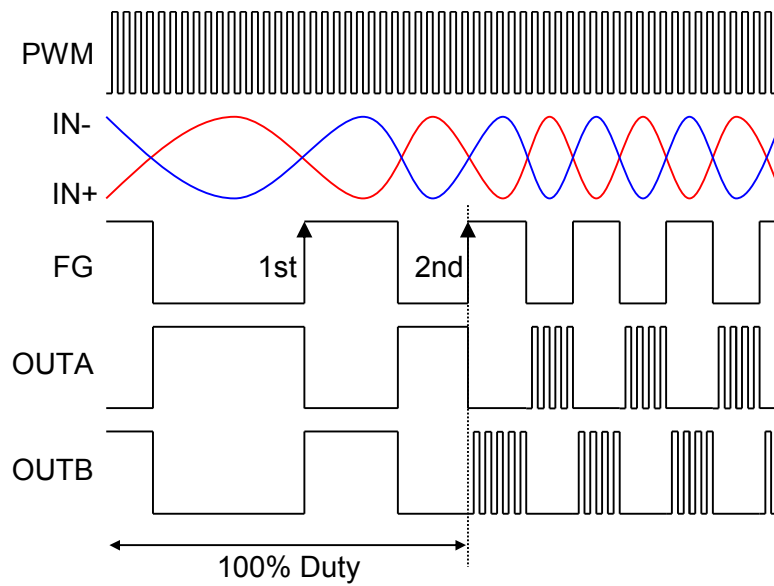
< Lock Protection Function >



< Quick Start Function >



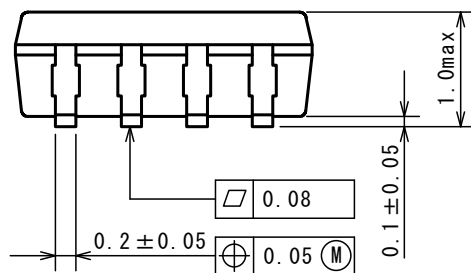
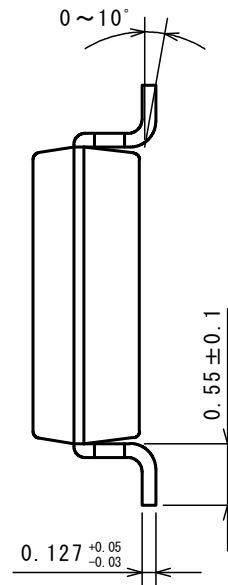
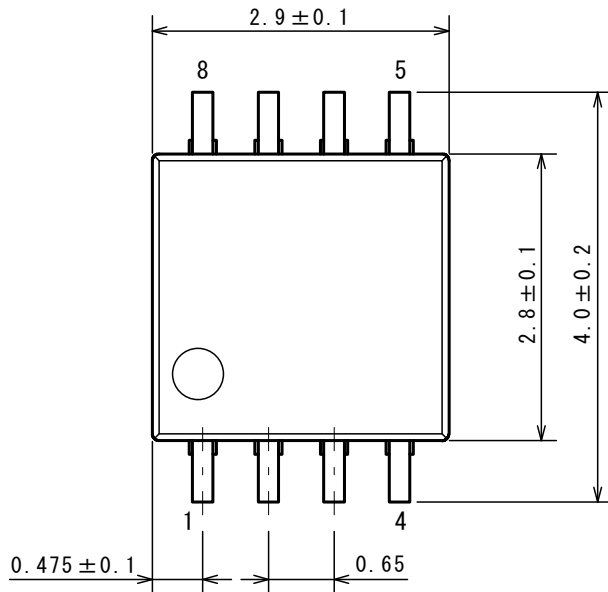
< Start up Assist Function >



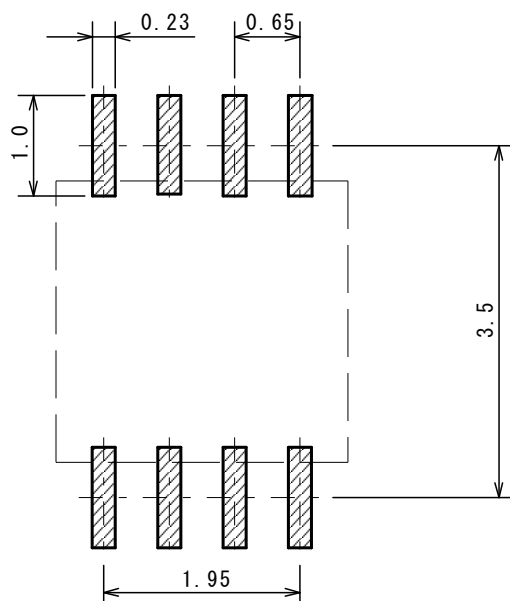
MSOP8 JEDEC MO-187-DA/THIN TYPE

Unit: mm

■ PACKAGE DIMENSIONS



■ EXAMPLE OF SOLDER PADS DIMENSIONS

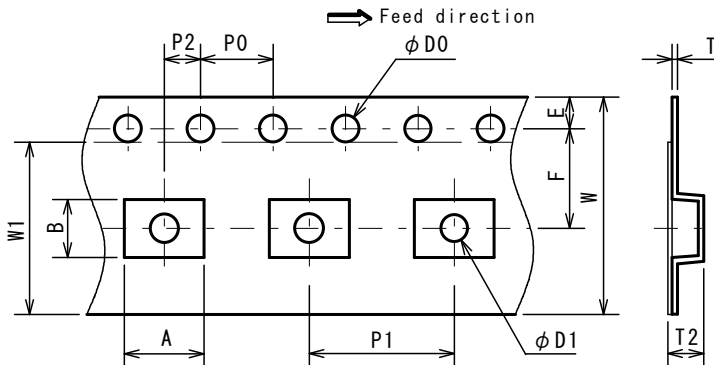


MSOP8 MEET JEDEC MO-187-DA/THIN TYPE

PACKING SPEC

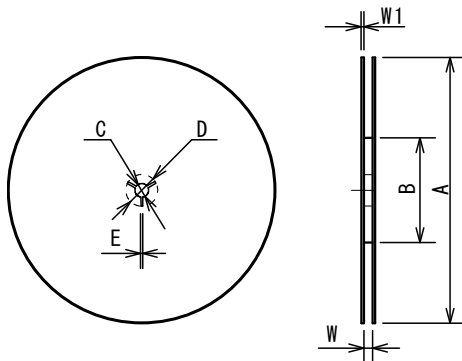
Unit: mm

TAPING DIMENSIONS



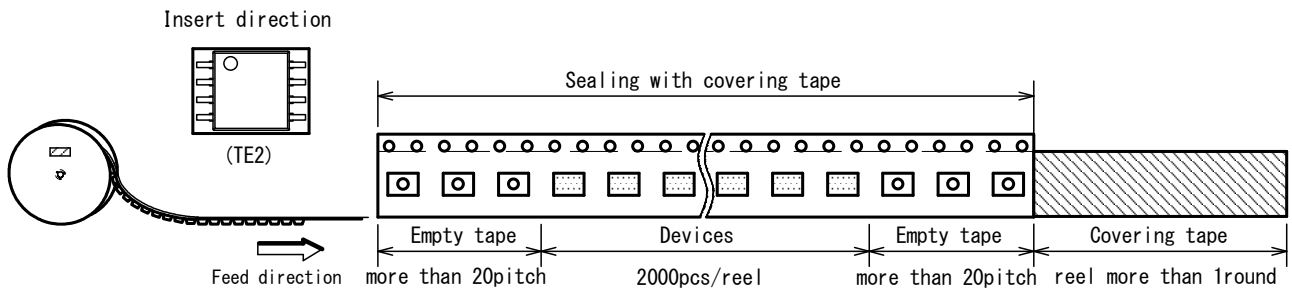
SYMBOL	DIMENSION	REMARKS
A	4.4	BOTTOM DIMENSION
B	3.2	BOTTOM DIMENSION
D0	$1.5^{+0.1}_0$	
D1	$1.5^{+0.1}_0$	
E	1.75 ± 0.1	
F	5.5 ± 0.05	
P0	4.0 ± 0.1	
P1	8.0 ± 0.1	
P2	2.0 ± 0.05	
T	0.30 ± 0.05	
T2	1.75 (MAX.)	
W	12.0 ± 0.3	
W1	9.5	THICKNESS 0.1max

REEL DIMENSIONS

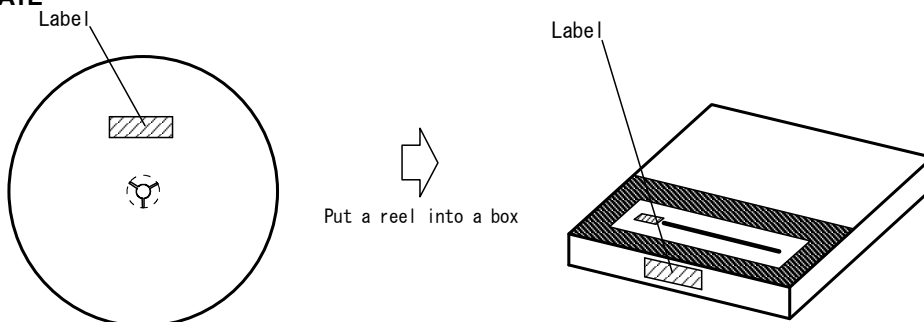


SYMBOL	DIMENSION
A	$\phi 254 \pm 2$
B	$\phi 100 \pm 1$
C	$\phi 13 \pm 0.2$
D	$\phi 21 \pm 0.8$
E	2 ± 0.5
W	13.5 ± 0.5
W1	2.0 ± 0.2

TAPING STATE



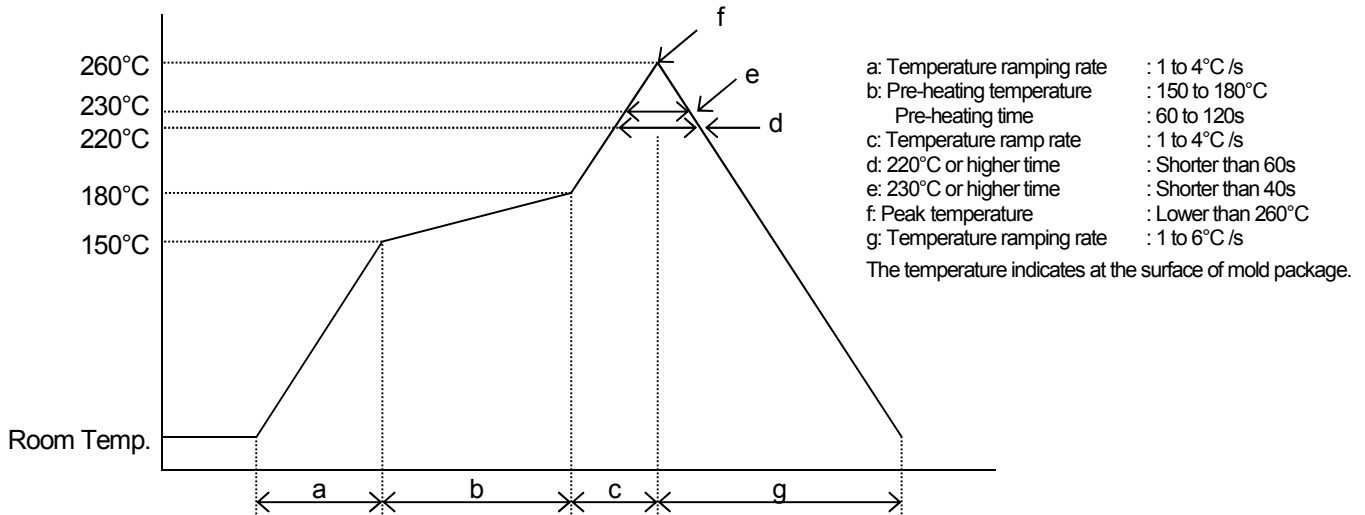
PACKING STATE



■RECOMMENDED MOUNTING METHOD

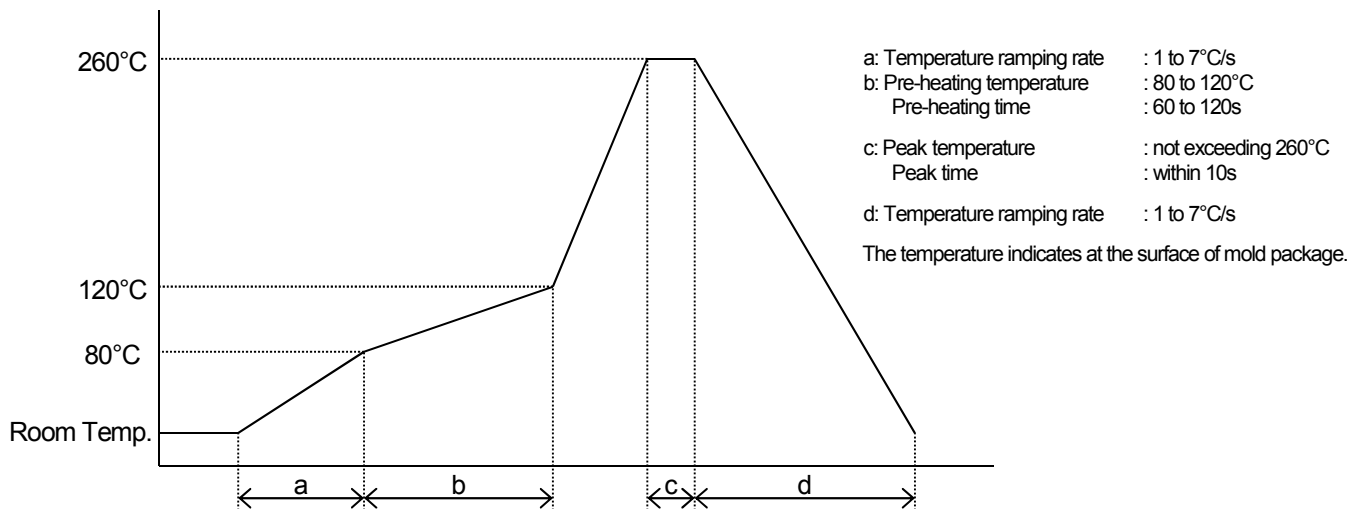
•INFRARED REFLOW SOLDERING METHOD

*reflow soldering procedure



•INFRARED FLOW SOLDERING METHOD

*flow soldering procedure



■REVISION HISTORY

Date	Revision	Changes
28.Nov.2016	Ver.1.0	New Release
07.Jun.2017	Ver.1.1	Corrected of PRODUCT NAME INFORMATION, ORDERING INFORMATION, THERMAL CHARACTERISTICS, PACKAGE DIMENSIONS, EXAMPLE OF SOLDER PADS DIMENSIONS and PACKING SPEC.

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